



INA2141

Dual, Low Power, G = 10, 100 INSTRUMENTATION AMPLIFIER

FEATURES

- LOW OFFSET VOLTAGE: 50µV max
- LOW DRIFT: 0.5μV/°C max
- EXCELLENT GAIN ACCURACY: ±0.05% max at G = 10
- LOW INPUT BIAS CURRENT: 5nA max
- HIGH CMR: 117dB min (G = 100)
- INPUTS PROTECTED TO ±40V
- WIDE SUPPLY RANGE: ±2.25V to ±18V
 LOW QUIESCENT CURRENT: 750µA/IA
- 16-PIN PLASTIC DIP, SOL-16

APPLICATIONS

- SENSOR AMPLIFIER THERMOCOUPLE, RTD, BRIDGE
- MEDICAL INSTRUMENTATION
- MULTIPLE CHANNEL SYSTEMS

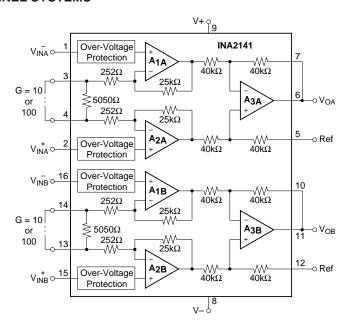
DESCRIPTION

The INA2141 is a low power, dual instrumentation amplifier offering excellent accuracy. Its versatile 3-op amp design and small size make it ideal for a wide range of applications. Current-feedback input circuitry provides wide bandwidth even at high gain (200 kHz) at G = 100.

Simple pin connections set an accurate gain of 10 or 100V/V without external resistors. Internal input protection can withstand up to $\pm 40V$ without damage.

The INA2141 is laser trimmed for very low offset voltage (50 μ V), drift (0.5 μ V/°C) and high common-mode rejection (117dB at G = 100). It operates with power supplies as low as ± 2.25 V, and quiescent current is only 750 μ A per amplifier—ideal for battery operated systems.

Packages are 16-pin plastic DIP, and SOL-16 surface-mount, specified for the -40°C to +85°C temperature range.



International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85706 • Tel: (520) 746-1111 • Twx: 910-952-1111 Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

At T_A= +25°C, V_S= $\pm 15 \text{V},$ and R_L= $10 k\Omega,$ unless otherwise noted.

| | | | INA2141P, U | | I | | | |
|---|--|--------------------------|---|--|-----------|---|---|--|
| PARAMETER | CONDITIONS | MIN | TYP | MAX | MIN | TYP | MAX | UNITS |
| INPUT Offset Voltage, RTI vs Temperature vs Power Supply Long-Term Stability Impedance, Differential Common-Mode Common-Mode Voltage Rang | $G = 100$ $G = 10$ $G = 100$ $G = 10^{(2)}$ $V_S = \pm 2.25 \text{ to } \pm 18\text{V}, G = 100$ $G = 10$ $G = 100$ $G = 10$ $V_O = 0\text{V}$ | (V+) - 2 (V-) + 2 | ±20 ±50 ±0.2 ±0.5 ±1 ±2 0.5 10 ¹⁰ 2 10 ¹⁰ 9 (V+) - 1.4 (V-) + 1.7 | ±50 ±100 ±0.5 ±2 ±2 ±10 | * | * | ±125 ±250 ±1.5 ±5 ±5 ±20 | μV μV μV/°C μV/°C μV/V μV/V μV/M Ω (|
| Common-Mode Rejection | $V_{CM} = \pm 13V$, $\Delta R_S = 1k\Omega$ G = 100 G = 10 | 117 97 | 125 106 | | 110 93 | 120 100 | | dB dB |
| BIAS CURRENT vs Temperature Offset Current vs Temperature | | | ±2 ±30 ±1 ±30 | ±5 ±5 | | * * * * | ±10 ±10 | nA pA/°C nA pA/°C |
| NOISE VOLTAGE, RTI $f = 10Hz$ $f = 10Hz$ $f = 100Hz$ $f = 10Hz$ $f = 10Hz$ to $10Hz$ $f = 10Hz$ $f = 10Hz$ $f = 10Hz$ $f = 10Hz$ to $10Hz$ Noise Current $f = 10Hz$ $f = 0.1Hz$ to $10Hz$ | $G = 100, R_S = 0\Omega$ $G = 10, R_S = 0\Omega$ | | 10 8 8 0.2 22 13 12 0.6 | | | **** | | nV//Hz nV//Hz nV//Hz nV//Hz pV/-P nV//Hz nV//Hz nV//Hz pA//Hz pA//Hz pAp-p |
| GAIN Gain Error Gain vs Temperature ⁽²⁾ Nonlinearity | V _O = ±13.6V, G = 100 G = 10 G = 10, 100 G = 100 G = 10 | | ±0.03 ±0.01 ±2 ±0.0005 ±0.0003 | ±0.075 ±0.05 ±10 ±0.002 ±0.001 | | * * * * | ±0.15 ±0.15 * ±0.004 ±0.002 | % % ppm/°C % of FSR % of FSR |
| OUTPUT Voltage: Positive Negative Load Capacitance Stability Short-Circuit Current | $R_L = 10$ kΩ $R_L = 10$ kΩ | (V+) - 1.4 (V-) + 1.4 | (V+) - 0.9 (V-) + 0.9 1000 +6/-15 | | * | * * * * | | V V pF mA |
| FREQUENCY RESPONSE Bandwidth, -3dB Slew Rate Settling Time, 0.01% Overload Recovery | G = 100 G = 10 $V_0 = \pm 10V, G = 10$ $V_0 = \pm 5V, G = 100$ G = 10 50% Overdrive | | 200 1 4 9 7 4 | | | * * * * * | | kHz MHz V/μs μs μs μs |
| POWER SUPPLY Voltage Range Current, Total | V _{IN} = 0V | ±2.25 | ±15 ±1.5 | ±18 ±1.6 | * | * * | * | V mA |
| | *** | -40 -40 | 80 | 85 125 | * | * | * | °C/W |

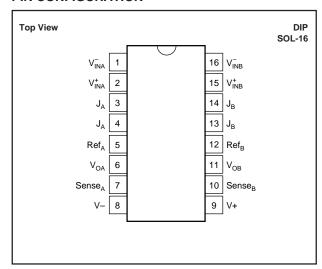
^{*} Specification same as INA2141P, U.

NOTE: (1) Input common-mode range varies with output voltage—see typical curves. (2) Guaranteed by wafer test.

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PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS

| Supply Voltage | ±18V |
|-----------------------------------|----------------|
| Analog Input Voltage Range | |
| Output Short-Circuit (to ground) | Continuous |
| Operating Temperature | 40°C to +125°C |
| Storage Temperature | 40°C to +125°C |
| Junction Temperature | +150°C |
| Lead Temperature (soldering, 10s) | +300°C |



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

| PRODUCT | PACKAGE | PACKAGE DRAWING NUMBER ⁽¹⁾ | TEMPERATURE RANGE | | |
|-----------|----------------------|---|----------------------|--|--|
| INA2141PA | 16-Pin Plastic DIP | 180 | -40°C to +85°C | | |
| INA2141P | 16-Pin Plastic DIP | 180 | -40°C to +85°C | | |
| INA2141UA | SOL-16 Surface-Mount | 211 | -40°C to +85°C | | |
| INA2141U | SOL-16 Surface-Mount | 211 | -40°C to +85°C | | |

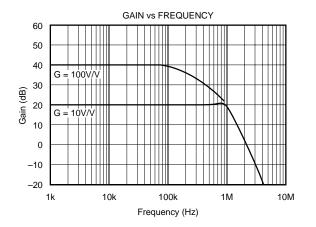
NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

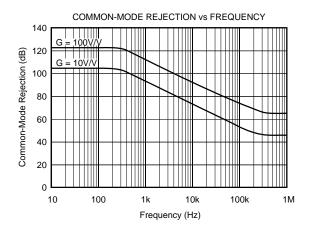
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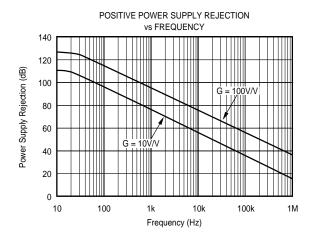
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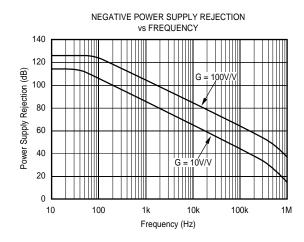
TYPICAL PERFORMANCE CURVES

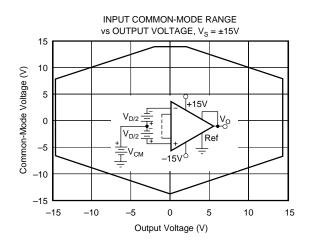
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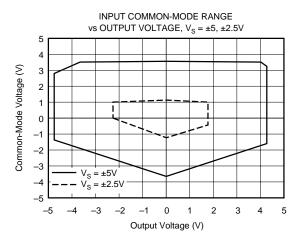






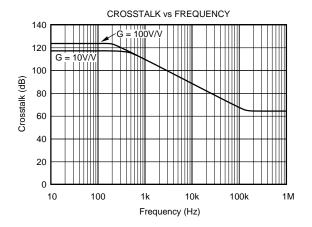


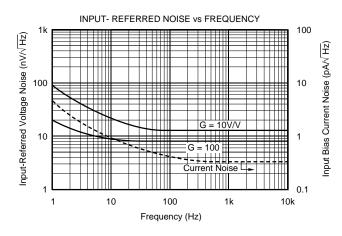


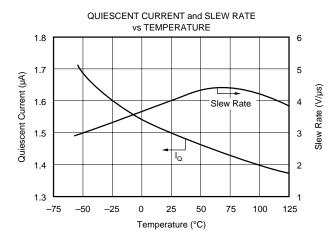


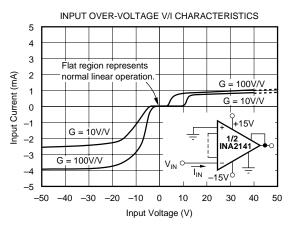
TYPICAL PERFORMANCE CURVES (CONT)

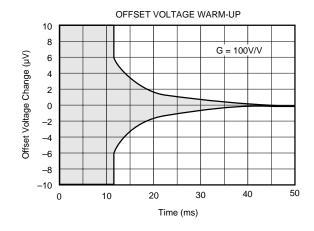
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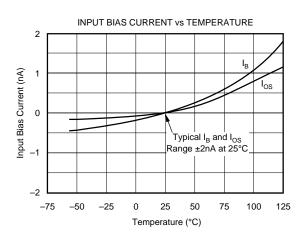






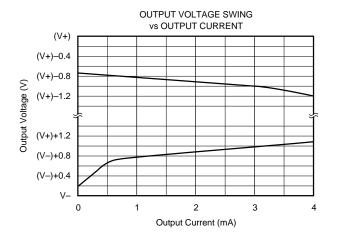


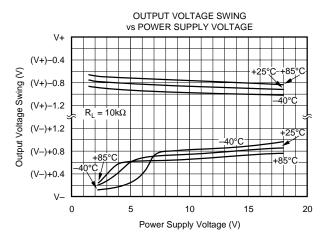


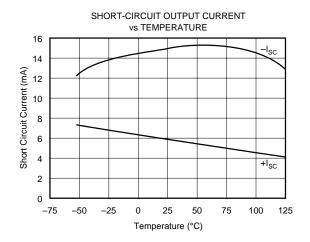


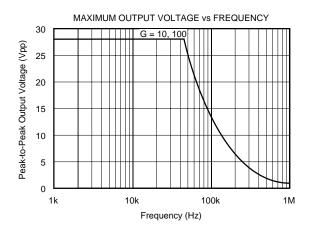
TYPICAL PERFORMANCE CURVES (CONT)

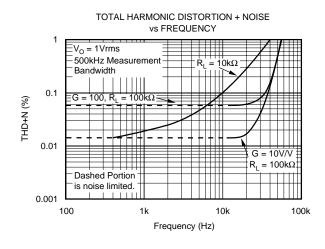
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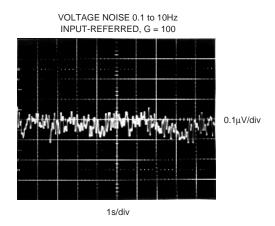








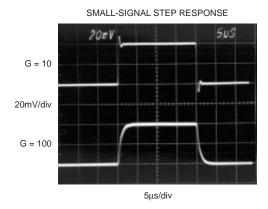


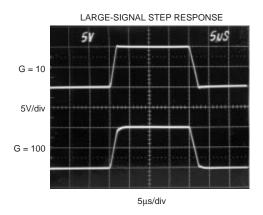




TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, and V_S = ±15V unless otherwise noted.





7

APPLICATION INFORMATION

Figure 1 shows the basic connections required for operation of the INA2141. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminals (Ref_A and Ref_B) which are normally grounded. These must be low-impedance connections to assure good common-mode rejection. A resistance of 8Ω in series with a Ref pin will cause a typical device to degrade to approximately 80dB CMR (G=1).

The INA2141 has a separate output sense feedback connections Sense_A and Sense_B. These must be connected to their respective output terminals for proper operation. The output sense connection can be used to sense the output voltage directly at the load for best accuracy.

SETTING THE GAIN

Gain of each IA can be independently selected with a jumper connection as shown in Figure 1. G=10V/V with no jumper installed. With a jumper installed G=100V/V. To preserve good gain accuracy, this jumper must have low series resistance. A resistance of 0.5Ω in series with the jumper will decrease the gain by 0.1%.

Internal resistor ratios are laser trimmed to assure excellent gain accuracy. Actual resistor values can vary by approximately $\pm 25\%$ from the nominal values shown.

Gains between 10 and 100 can be achieved by connecting an external resistor to the jumper pins. This is not recommended, however, because the ±25% variation of internal resistor values makes the required external resistor value uncertain. A companion model, INA2128, features accurately trimmed internal resistors so that gains from 1 to 10.000 can be set with an external resistor.

DYNAMIC PERFORMANCE

The typical performance curve "Gain vs Frequency" shows that despite its low quiescent current, the INA2141 achieves wide bandwidth, even at high gain. This is due to its current-feedback topology. Settling time also remains excellent at high gain.

NOISE PERFORMANCE

The INA2141 provides very low noise in most applications. Low frequency noise is approximately $0.2\mu\text{Vp-p}$ measured from 0.1 to 10Hz (G = 100). This provides dramatically improved noise when compared to state-of-the-art chopper-stabilized amplifiers.

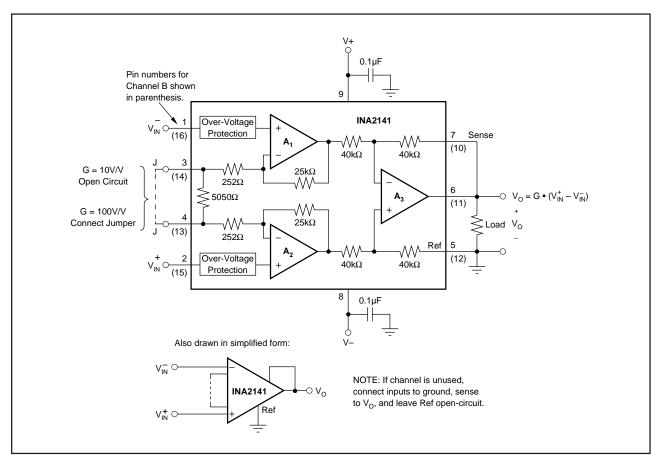


FIGURE 1. Basic Connections.



OFFSET TRIMMING

The INA2141 is laser trimmed for low offset voltage and offset voltage drift. Most applications require no external offset adjustment. Figure 2 shows an optional circuit for trimming the output offset voltage. The voltage applied to Ref terminal is summed with the output. The op amp buffer provides low impedance at the Ref terminal to preserve good common-mode rejection.

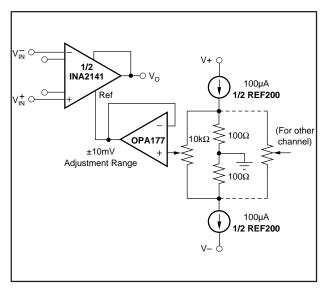


FIGURE 2. Optional Trimming of Output Offset Voltage.

INPUT BIAS CURRENT RETURN PATH

The input impedance of the INA2141 is extremely high—approximately $10^{10}\Omega$. However, a path must be provided for the input bias current of both inputs. This input bias current is approximately $\pm 2nA$. High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current for proper operation. Figure 3 shows various provisions for an input bias current path. Without a bias current path, the inputs will float to a potential which exceeds the common-mode range of the INA2141 and the input amplifiers will saturate.

If the differential source resistance is low, the bias current return path can be connected to one input (see the thermocouple example in Figure 3). With higher source impedance, using two equal resistors provides a balanced input with possible advantages of lower input offset voltage due to bias current and better high-frequency common-mode rejection.

INPUT COMMON-MODE RANGE

The linear input voltage range of the input circuitry of the INA2141 is from approximately 1.4V below the positive supply voltage to 1.7V above the negative supply. As a differential input voltage causes the output voltage increase, however, the linear input range will be limited by the output voltage swing of amplifiers A₁ and A₂. So the linear com-

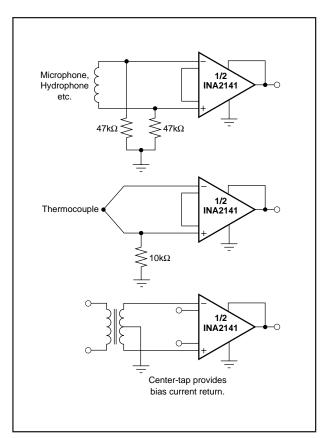


FIGURE 3. Providing an Input Common-Mode Current Path.

mon-mode input range is related to the output voltage of the complete amplifier. This behavior also depends on supply voltage—see performance curves "Input Common-Mode Range vs Output Voltage".

Input-overload can produce an output voltage that appears normal. For example, if an input overload condition drives both input amplifiers to their positive output swing limit, the difference voltage measured by the output amplifier will be near zero. The output of the INA2141 will be near 0V even though both inputs are overloaded.

LOW VOLTAGE OPERATION

The INA2141 can be operated on power supplies as low as ± 2.25 V. Performance remains excellent with power supplies ranging from ± 2.25 V to ± 18 V. Most parameters vary only slightly throughout this supply voltage range—see typical performance curves. Operation at very low supply voltage requires careful attention to assure that the input voltages remain within their linear range. Voltage swing requirements of internal nodes limit the input commonmode range with low power supply voltage. Typical performance curves, "Input Common-Mode Range vs Output Voltage" show the range of linear operation for ± 15 V, ± 5 V, and ± 2.5 V supplies.



9

INPUT PROTECTION

The inputs of the INA2141 are individually protected for voltages up to $\pm 40 \text{V}$. For example, a condition of -40 V on one input and +40 V on the other input will not cause damage. Internal circuitry on each input provides low series impedance under normal signal conditions. To provide equivalent protection, series input resistors would contribute excessive noise. If the input is overloaded, the protection circuitry limits the input current to a safe value of approximately 1.5 to 5mA. The typical performance curve "Input Bias Current vs Common-Mode Input Voltage" shows this input current limit behavior. The inputs are protected even if the power supplies are disconnected or turned off.

CHANNEL CROSSTALK

The two channels of the INA2141 are completely independent, including all bias circuitry. At DC and low frequency

there is virtually no signal coupling between channels. Crosstalk increases with frequency and is dependent on circuit gain, source impedance and signal characteristics.

As source impedance increases, careful circuit layout will help achieve lowest channel crosstalk. Most crossstalk is produced by capacitive coupling of signals from one channel to the input section of the other channel. To minimize coupling, separate the input traces as far as practical from any signals associated with the opposite channel. A grounded guard trace surrounding the inputs helps reduce stray coupling between channels. Run the differential inputs of each channel parallel to each other or directly adjacent on top and bottom side of a circuit board. Stray coupling then tends to produce a common-mode signal which is rejected by the IA's input.

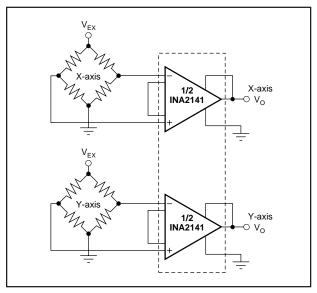


FIGURE 4. Two-Axis Bridge Amplifier.

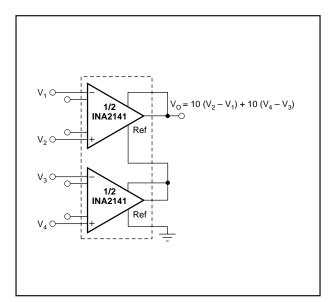


FIGURE 5. Sum of Differences Amplifier.

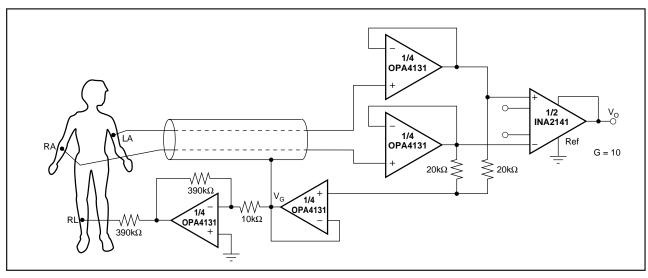


FIGURE 6. ECG Amplifier With Right-Leg Drive.







11-Jul-2013

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package | Pins | Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|----------|--------------|---------|------|---------|----------------------------|------------------|---------------------|--------------|----------------|---------|
| | (1) | | Drawing | | Qty | (2) | | (3) | | (4/5) | |
| INA2141P | OBSOLETE | PDIP | N | 16 | | TBD | Call TI | Call TI | | | |
| INA2141PA | OBSOLETE | PDIP | N | 16 | | TBD | Call TI | Call TI | | | |
| INA2141U | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2141U A | Samples |
| INA2141UA | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2141U A | Samples |
| INA2141UA/1K | ACTIVE | SOIC | DW | 16 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2141U A | Samples |
| INA2141UA/1KE4 | ACTIVE | SOIC | DW | 16 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2141U A | Samples |
| INA2141UAE4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | | INA2141U A | Samples |
| INA2141UE4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 85 | INA2141U A | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

11-Jul-2013

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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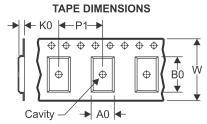
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| INA2141UA/1K | SOIC | DW | 16 | 1000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |

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*All dimensions are nominal

| ĺ | Device | Device Package Type | | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|---|--------------|---------------------|----|------|------|-------------|------------|-------------|--|
| | INA2141UA/1K | SOIC | DW | 16 | 1000 | 367.0 | 367.0 | 38.0 | |

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